



Low temperature joining is allowing new applications

Henkel to Host IMAPS-UK Workshop on Low Temperature Joining

Henkel Adhesive Technologies and IMAPS-UK have announced that the society's next educational workshop, which is focused on low temperature joining, will take place at Henkel's Hemel Hempstead, UK facility on January 28, 2016. This is one of approximately five UK-based IMAPS educational workshops available to electronics professionals over the next year.

"The topic of low temperature joining is particularly relevant in today's era of wearable devices and other flexible, 'non-mission-critical' applications," explains Henkel Technical Support Engineer, Tony Winster, who was instrumental in organizing the IMAPS-UK event. "While many electronics devices used in extremely high-reliability applications need to work over a wide operating temperature range for a long time, numerous products simply don't fall into that category. For devices that don't need to be processed at high temperatures with more costly materials, low temperature joining is allowing new applications to be brought to market."

Several novel devices are leveraging printed electronics technologies to enable the production of flexible, plastic substrates that can only withstand low temperature processing (less than 120° C). The aim of the IMAPS-UK workshop is to address these emerging applications, the materials used to manufacture them and the process parameters required for high-volume production.

"We are grateful for the opportunity to host this important event at Henkel's newlyrenovated Hemel Hempstead facility," says Chris Hunt, Vice-Chairman of IMAPS-UK and Technical Leader at the National Physical Laboratory. "The line-up of speakers is impressive and will no doubt deliver an exceptional and insightful program for those in attendance."



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Presenters and topics for the January 28th event include:

- Henkel Adhesive Technologies Key Note Speech: Market and Technical Challenges and Solutions
- Gwent Electronics Printed Inks and Coatings
- Henkel Adhesive Technologies Low-Temperature Processing Conductive Adhesives
- Center for Process Innovation Supply Chain for Low Temperature Devices
- National Physical Laboratory Testing Considerations
- Case Study Pragmatic, Organic Transistor Chip Manufacturer
- Case Study Novalia, Designer of Printed Electronic Devices
- The Fraunhofer EMFT Institute Hybrid Integration for Plastic Film Electronics

"As we move into the era of wearable devices and sensor applications for the Internet of Things, low temperature joining becomes a key enabler," notes Winster in conclusion. "This IMAPS event is an exceptional opportunity to hear from some of the leading experts in this area."

For more information or to register for the event, visit www.imaps.org.uk.

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About Henkel

Henkel operates worldwide with leading brands and technologies in three business units: Laundry & Home Care, Beauty Care and Adhesive Technologies. Founded in 1876, Henkel holds globally leading market positions, both in the consumer and in the industrial businesses, with well-known brands such as Persil, Schwarzkopf and Loctite. Henkel employs about 50,000 people and reported sales of 16.4 billion euros and adjusted operating profit of 2.6 billion euros in fiscal 2014. Henkel's preferred shares are listed in the German stock index DAX.

Photo material is available at http://www.henkel.com/press

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The following material is available:



Henkel Adhesive Technologies - Low-Temperature Processing Conductive Adhesives



IMAPS UK